# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

[List multiple models if applicable.]

| HP 1000 Notebook PC |

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>5</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).
Components, parts and materials containing refractory ceramic fibers | 0
Components, parts and materials containing radioactive substances | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Motor Screw Driver &quot;+&quot;</td>
<td>Cross head of screwdriver</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Reverse machine, poke battery lock, and then take out battery.
2. Loosen RAM cover screw *1, take out RAM cover
3. Loosen HDD cover screw *1, take out HDD cover
4. Pull HDD rubber, pull out HDD module
5. Pull out HDD cable, take out HDD
6. Disassemble ODD Cable
7. Loosen ODD screw *1, Pull out ODD
8. Pull out WLAN cable *2
9. Loosen screw *1, take out WLAN card
10. Loosen BTCB screw *22 in order
11. Reverse machine and disassemble K/B
12. Disassemble K/B FFC
13. Disassemble Touch Pad FFC, Power/B FFC
14. Loosen Top case screw *2
15. Disassemble Top case
16. Disassemble USB/B FFC
17. Loosen screw *1, take out USB/B
18. Pull out DC in IO port
19. Remove the tape of LVDS CNTR, pull out LVDS Cable
20. Take out HDD Lens Rubber
21. Loosen LCM screw *5 in order, take out LCM
22. Loosen M/B screw *2 in order
23. Pull Out Speaker Cable,
24. Disassemble M/B
25. Loosen screw *1, Take out ODD Bracket, ODD Cable
26. Pull out ODD Cable and Speaker
27. Loosen CPU socket screw by using one-line screw driver
28. Pull out Fan Cable, Pull out DC in cable
29. Loosen screws *2 in order, take out the fan(UMA), Loosen screws *3 in order, take out the fan(DIS)
30. Loosen thermal module screws *4 in order, Take out Thermal Module
31. Disassemble DDR
32. Take out the Mylar *2 form hinge screw holes, Loosen Bezel screw *2 in order

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Template Revision B

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33. Disassemble TPDL in order
34. Loosen Hinge cover-R screw, take out the cover
35. Loosen Hinge side cover R screw, take out the side cover
36. Loosen Hinge cover-L screw, take out the cover
37. Loosen Hinge side cover L screw, take out the side cover
38. Pull out LCM Cable
39. Loosen Hinge Bracket screw *8 in order
40. Separate LCD from BTDL
41. Disassemble Camera, Disassemble LVDS cable Module, Separate LVDS Cable from LCD
42. Pull out WLAN-Main Antenna from BTDL
43. Pull out WLAN-AUX Antenna from BTDL
44. Remove Aluminum foil, take out WLAN Antenna-R (MAIN), Remove Aluminum foil, take out WLAN Antenna-L (AUX)
45. 3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly
3.22 Remove battery module
3.23 Remove service door
3.24 LCD module set disassembly
3.25 Top case disassembly
3.26 Thermal module and mother board disassembly
3.27 Bottom case disassembly